

Product Summary

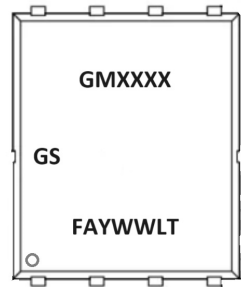
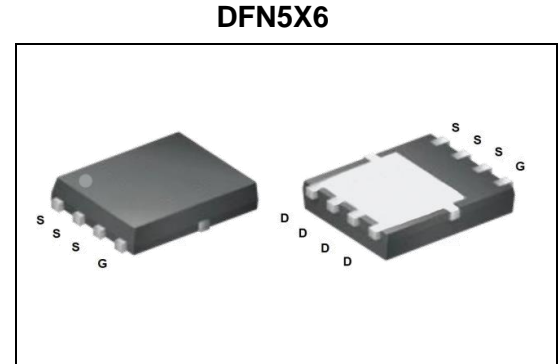
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HEXÁ	1.5{ ô Á Ö Å Ö Û Á Á É X Á	185AA
	G6{ ô Á Ö Å Ö Û Á Á É X Á	

Features

- Low R_{DS(on)} trench technology
- Low thermal impedance
- Fast switching speed
- 100% avalanche tested

Application

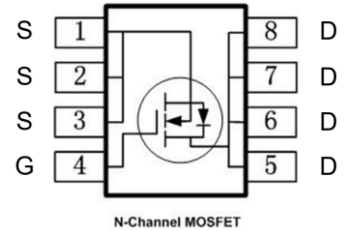
- DC/DC conversion
- Power switch
- Motor drives
- Li- Battery Protection



DFN5X6

NOTE:
 LOGO - GS
 GMXXXXX- Part number code
 F - Fab location code
 A - Assembly location code
 Y - Year code
 WW - Week code
 L&T - Assembly lot code

Equivalent circuit



CfXYf]b['bZ'fa U]cb'

DUFhBi a VYf'	7 Ugy'	DUW U]]b['
GMS016N03E4Á	ÖÖÍ YÍ Á	5ÉÉÉVá ^ Á Á ^ Á

Öá [] c'Á aqã ~ { ÁÜaa * ÁVaaG xÖD

DUFUa YhYg'	Gna Vc''	A U'	I b]hg'
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Thermal Characteristics

Characteristic		Symbol	Typ	Max	Unit
Maximum Junction-to-Ambient ^A	$t \leq 10s$	$R_{\theta JA}$	16	20	$^{\circ}C/W$
Maximum Junction-to-Ambient ^{A D}	Steady-State		38.5	55	$^{\circ}C/W$
Maximum Junction-to-Case	Steady-State	$R_{\theta JC}$	1.13	1.4	$^{\circ}C/W$

Electrical Characteristics (@T_J = +25°C unless otherwise specified.)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=250\mu A, V_{GS}=0V$	30			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=30V, V_{GS}=0V$			1	μA
		$T_J=55^{\circ}C$			5	
I_{GSS}	Gate-Body leakage current	$V_{DS}=0V, V_{GS}=\pm 20V$			± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	1.2	1.5	2.4	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS}=10V, I_D=20A$		1.2	1.5	m Ω
		$T_J=125^{\circ}C$		1.9	2.4	
		$V_{GS}=4.5V, I_D=20A$		1.6	2.6	m Ω
g_{FS}	Forward Trans conductance	$V_{DS}=5V, I_D=20A$		129		S
V_{SD}	Diode Forward Voltage	$I_S=1A, V_{GS}=0V$		0.67	1	V
V_{SD}	Diode Forward Voltage	$I_S=85A, V_{GS}=0V$		0.87	1.3	V
I_S	Maximum Body-Diode Continuous Current				132	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0V, V_{DS}=15V,$ $f=1MHz$		3509		pF
C_{oss}	Output Capacitance			1847		pF
C_{riss}	Reverse Transfer Capacitance			86		pF
R_g	Gate resistance	$f=1MHz$	0.7	1.5	2.3	Ω
SWITCHING PARAMETERS						
$Q_g(10V)$	Total Gate Charge	$V_{GS}=10V, V_{DS}=15V,$ $I_D=20A$		49		nC
Q_{gs}	Gate Source Charge			11.8		nC
Q_{gd}	Gate Drain Charge			6.8		nC
$t_{D(on)}$	Turn-On Delay Time	$V_{GS}=10V, V_{DS}=15V,$ $R_L=0.75\Omega, R_{GEN}=3\Omega$		13		ns
t_r	Turn-On Rise Time			63.6		ns
$t_{D(off)}$	Turn-Off Delay Time			38		ns
t_f	Turn-Off Fall Time			56		ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=20A, di/dt=100A/\mu s$		51.4		ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=20A, di/dt=100A/\mu s$		52		nC

A. The value of $R_{\theta JA}$ is measured with the device mounted on 1in²FR-4 board with 1oz. Copper, in a still air environment with $T_A=25^{\circ}C$. The value in any given application depends on the user's specific board design.

B. The power dissipation P_D is based on $T_{J(max)}=150^{\circ}C$, using junction-to-case thermal resistance and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C. Repetitive rating, pulse width limited by junction temperature $T_{J(max)}=150^{\circ}C$. Ratings are based on low frequency and duty cycles to keep initial $T_J=25^{\circ}C$.

D. The $R_{\theta JA}$ is the sum of the thermal impedance from junction to case $R_{\theta JC}$ and case to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using $<300\mu s$ pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a larger heatsink, assuming a maximum junction temperature of $T_J(max)=150^{\circ}C$. The SOA curve provides a single pulse rating

G. The maximum current rating is package limited

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

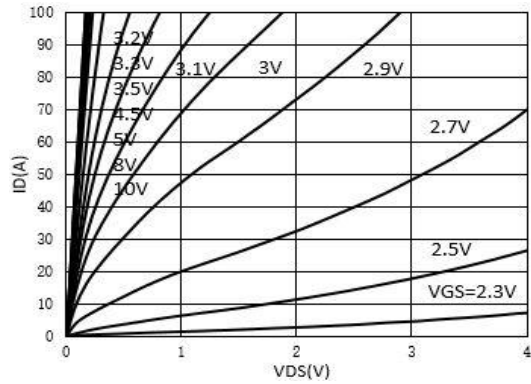


Figure 1: On-Region Characteristics(Note E)

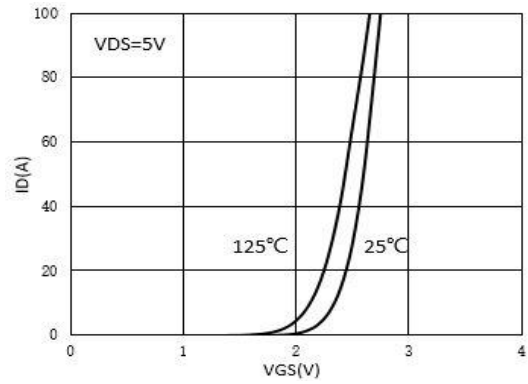


Figure 2: Transfer Characteristics(Note E)

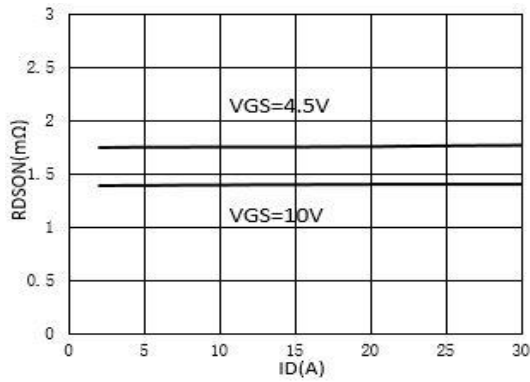


Figure 3: On-Resistance vs. Drain Current and Gate Voltage(Note E)

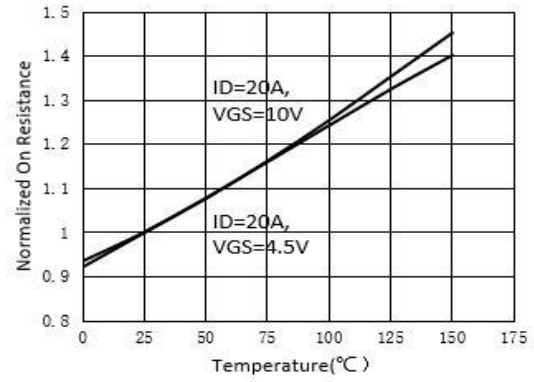


Figure 4: On-Resistance vs. Junction Temperature(Note E)

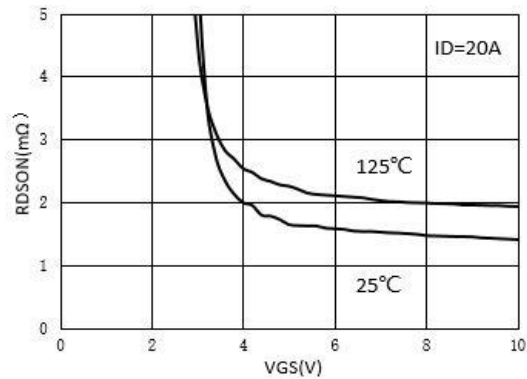


Figure 5: On-Resistance vs. Gate-Source Voltage(Note E)

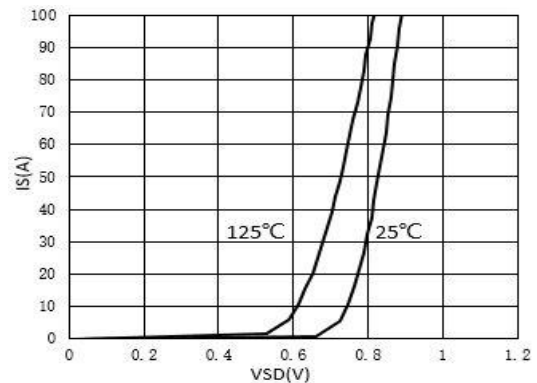


Figure 6: Body-Diode Characteristics (Note E)

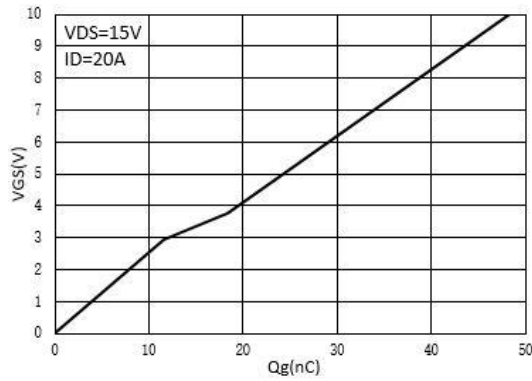


Figure 7: Gate-Charge Characteristics

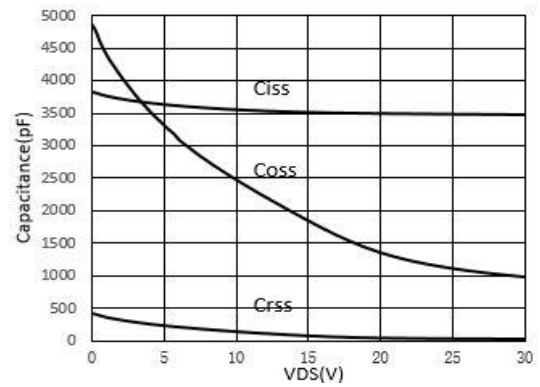


Figure 8: Capacitance Characteristics

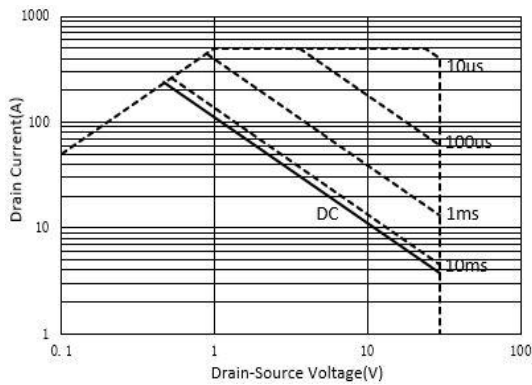


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

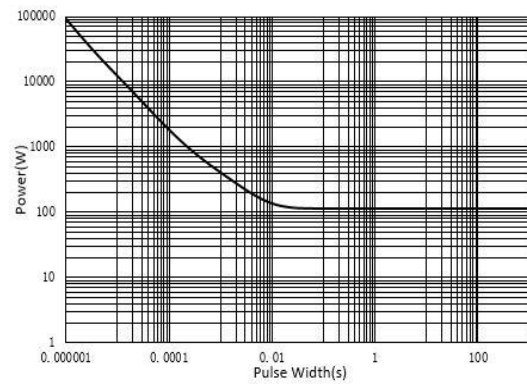


Figure 10: Single pulse Power Rating Junction-to-Case(Note F)

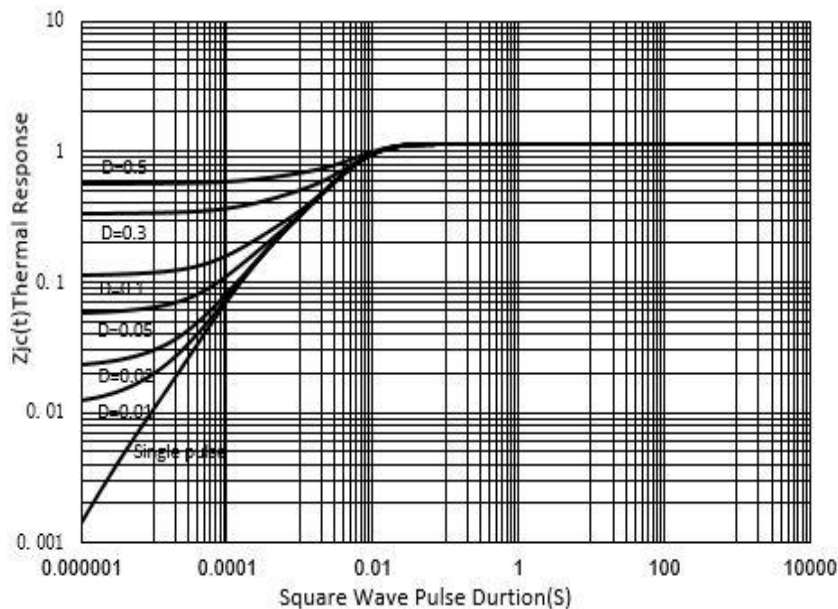
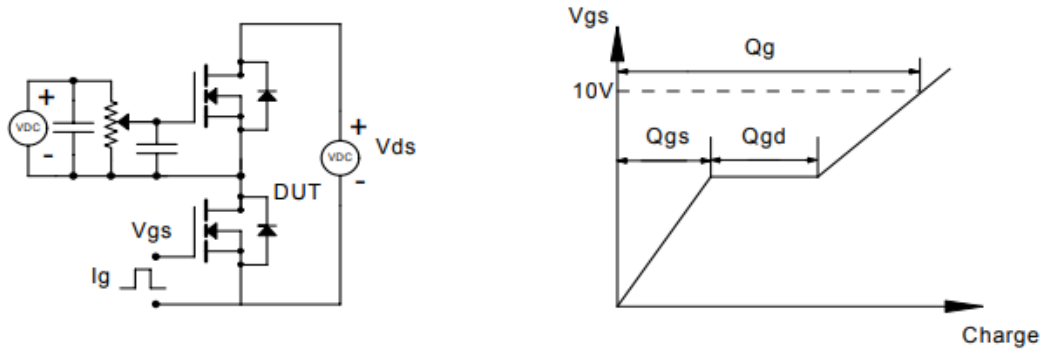


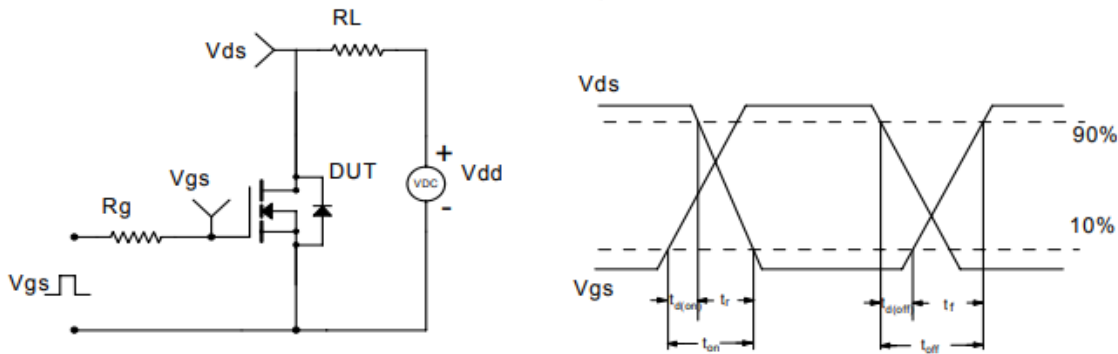
Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

Test Circuit

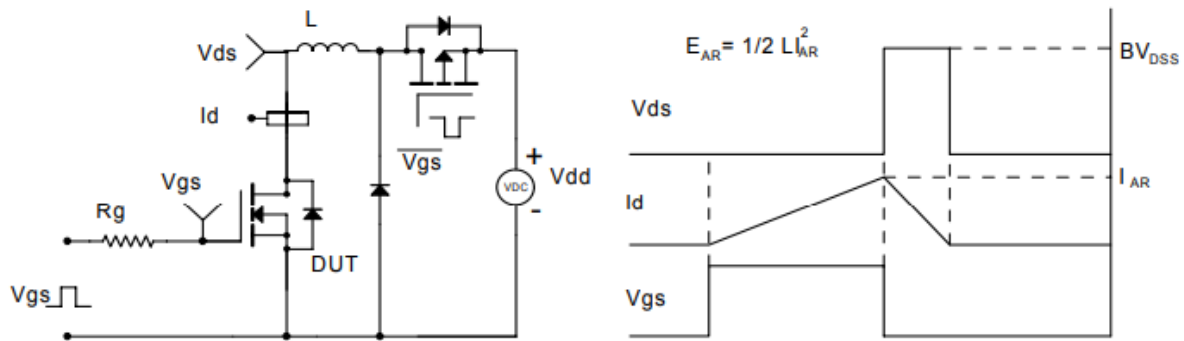
Gate Charge Test Circuit & Waveform



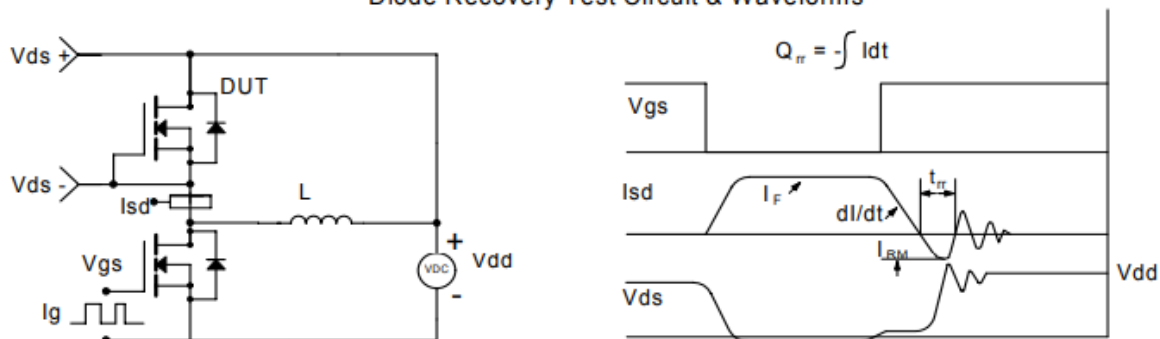
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

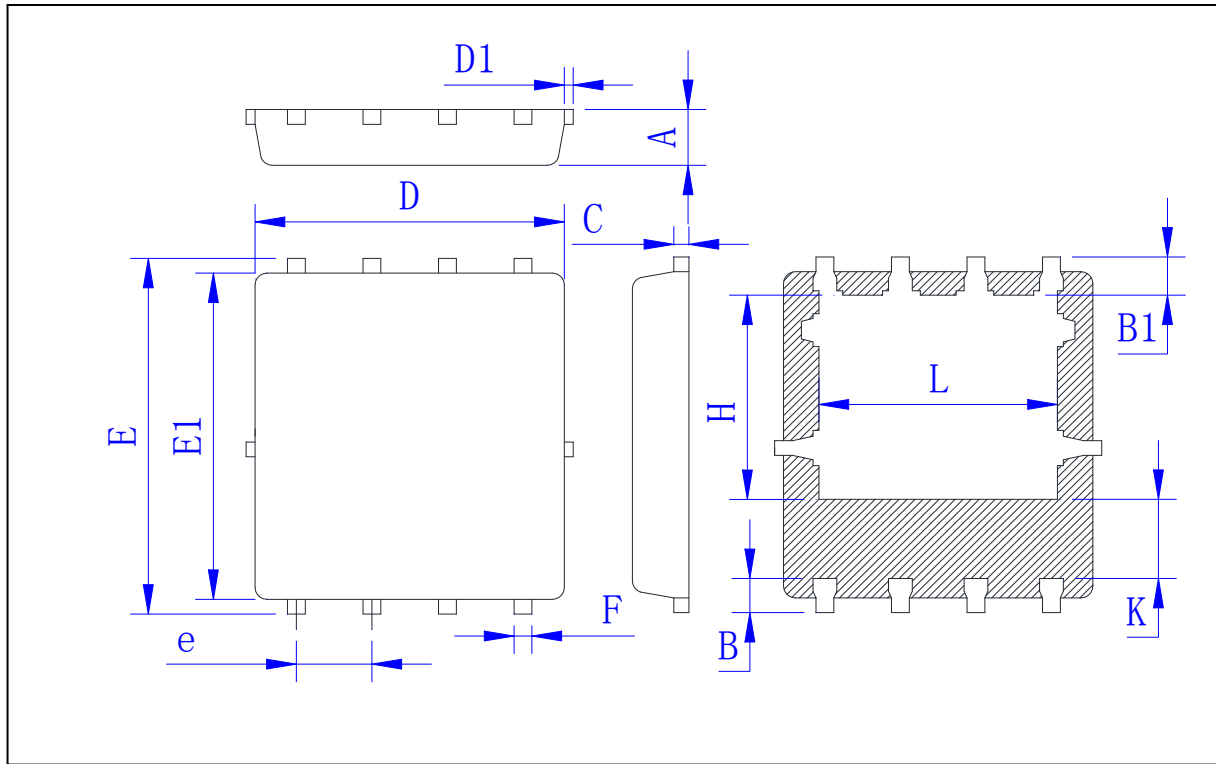


Diode Recovery Test Circuit & Waveforms





Package outline:DFN5x6



Symbol	Min	Typ	Max
A	0.90	0.95	1.00
B	0.48	0.58	0.68
B1	0.55	0.65	0.75
C	0.20	0.254	0.30
D	5.10	5.20	5.30
D1			0.15
E	5.90	6.05	6.20
E1	5.40	5.55	5.70
e	1.22	1.27	1.32
F	0.25	0.30	0.35
H	3.27	3.47	3.67
L	3.80	4.00	4.20
K	1.20		

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